



YETDA INDUSTRY LTD.

Technical Data Sheet

MODEL NO : S5630ANW4P

5.7 x 3.0 x 0.9mm SMD LED

Features :

- Package: 3000 pcs per reel
- Compatible with automatic placement equipment
- Compatible with reflow solder process

Applications :

- Indicators
- Automotive : backlighting in dashboard and switch
- Backlight for LCD

Dice material	Emitted color	Lens Color
InGaN	White	Yellow Fluorescent

Electrical/Optical Characteristics(Ta=25°C)

Parameter	Test Condition	Symbol	Value			Unit
			Min	Typ	Max	
Chromaticity Coordinates	I _F =150mA	X		0.32		-
		Y		0.33		-
Forward voltage	I _F =150mA	V _F	3.0		3.8	V
Luminous Intensity	I _F =150mA	I _v	15000		20000	mcd
Luminous Flux	I _F =150mA	φ _V		49		Lm
Color Temperature	I _F =150mA	CCT		6200		K
Color Rendering Index	I _F =150mA	CRI	70			Ra
Viewing angle at 50% I _v	I _F =150mA	2θ 1/2		120		Deg
Reverse current	V _R =5V	I _R			10	μA

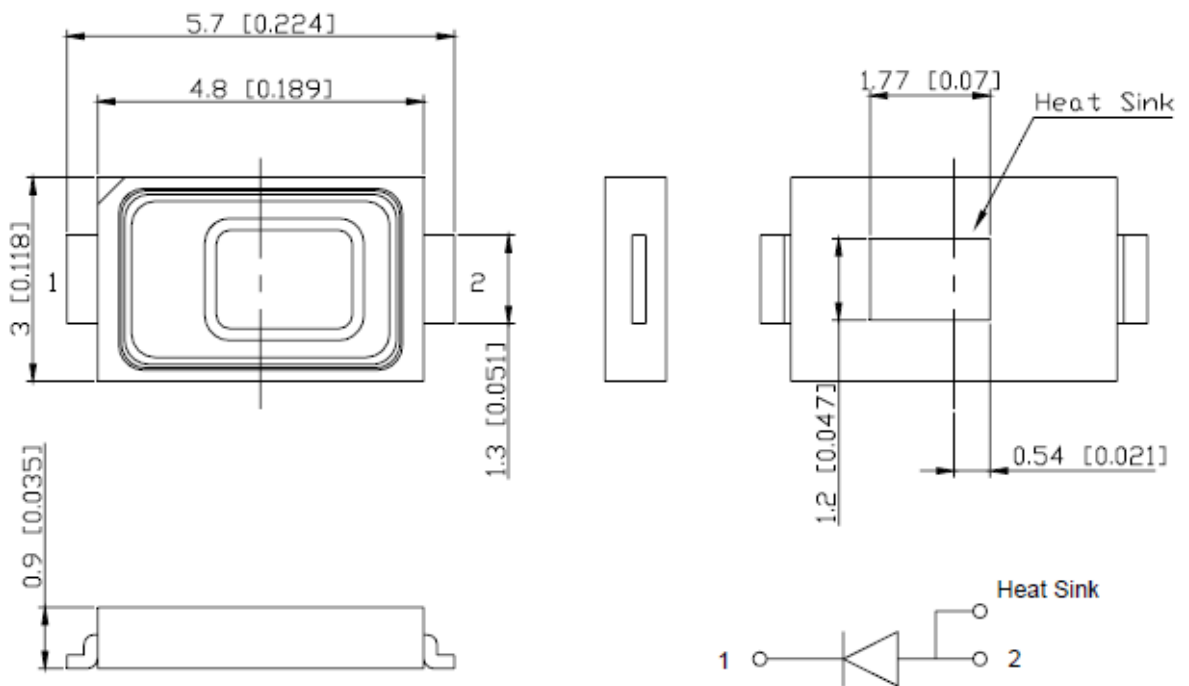
Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Value	Unit
Power dissipation	P _d	500	mW
Forward current	I _F	150	mA
Reverse voltage	V _R	5	V
Operating temperature range	T _{op}	-20 ~+80	°C
Storage temperature range	T _{stg}	-40 ~+80	°C
Peak pulsing current (1/10 duty f=1kHz)	I _{FP}	200	mA



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PACKAGING DIMENSIONS (mm):





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VF RANK

Rank	VF(V)		Condition
	Min	Max	
H	3.0	3.2	IF=150mA
J	3.2	3.4	
K	3.4	3.6	
L	3.6	3.8	

Tolerance:±0.1V

VF RANK

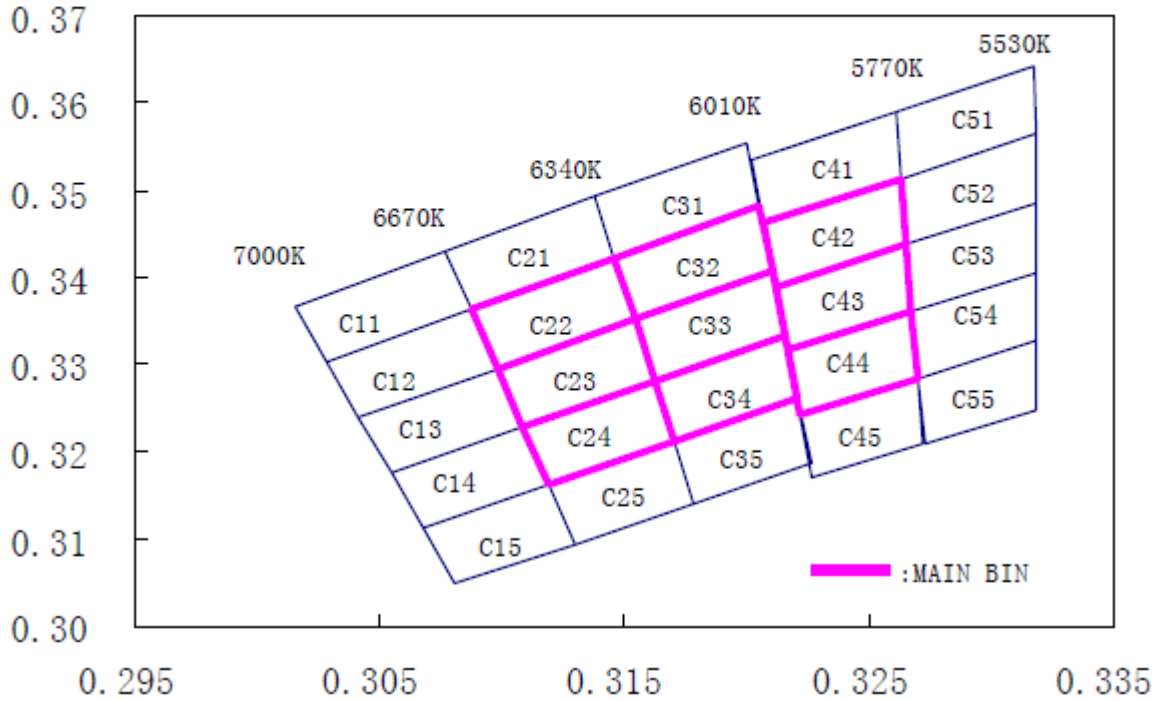
Rank	IV(mcd)		Condition
	Min	Max	
ZK	15000	18000	IF=150mA
ZL	18000	22000	

Tolerance:±15%



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X/Y Rank



Bin	x	y	Bin	x	y	Bin	x	y	Bin	x	y	Bin	x	y
C11	0.3015	0.3367	C21	0.3076	0.3430	C31	0.3138	0.3493	C41	0.3202	0.3535	C51	0.3261	0.3589
	0.3076	0.3430		0.3138	0.3493		0.3200	0.3555		0.3261	0.3589			
	0.3087	0.3363		0.3146	0.3422		0.3205	0.3481		0.3263	0.3513			
	0.3028	0.3304		0.3087	0.3363		0.3146	0.3422		0.3207	0.3462			
C12	0.3028	0.3304	C22	0.3087	0.3363	C32	0.3146	0.3422	C42	0.3207	0.3462	C52	0.3263	0.3513
	0.3087	0.3363		0.3146	0.3422		0.3205	0.3481		0.3263	0.3513			
	0.3098	0.3296		0.3154	0.3352		0.3210	0.3408		0.3265	0.3437			
	0.3041	0.3240		0.3098	0.3296		0.3154	0.3352		0.3212	0.3389			
C13	0.3041	0.3240	C23	0.3098	0.3296	C33	0.3154	0.3352	C43	0.3212	0.3389	C53	0.3265	0.3437
	0.3098	0.3296		0.3154	0.3352		0.3210	0.3408		0.3265	0.3437			
	0.3108	0.3229		0.3162	0.3282		0.3216	0.3334		0.3267	0.3361			
	0.3055	0.3177		0.3108	0.3229		0.3162	0.3282		0.3217	0.3316			
C14	0.3055	0.3177	C24	0.3108	0.3229	C34	0.3162	0.3282	C44	0.3217	0.3316	C54	0.3267	0.3361
	0.3108	0.3229		0.3162	0.3282		0.3216	0.3334		0.3267	0.3361			
	0.3119	0.3162		0.3170	0.3212		0.3221	0.3261		0.3270	0.3285			
	0.3068	0.3113		0.3119	0.3162		0.3170	0.3212		0.3222	0.3243			
C15	0.3068	0.3113	C25	0.3119	0.3162	C35	0.3170	0.3211	C45	0.3222	0.3243	C55	0.3270	0.3285
	0.3119	0.3162		0.3170	0.3211		0.3221	0.3261		0.3270	0.3285			
	0.3130	0.3095		0.3178	0.3141		0.3226	0.3188		0.3272	0.3209			
	0.3080	0.3050		0.3130	0.3095		0.3178	0.3141		0.3227	0.3170			

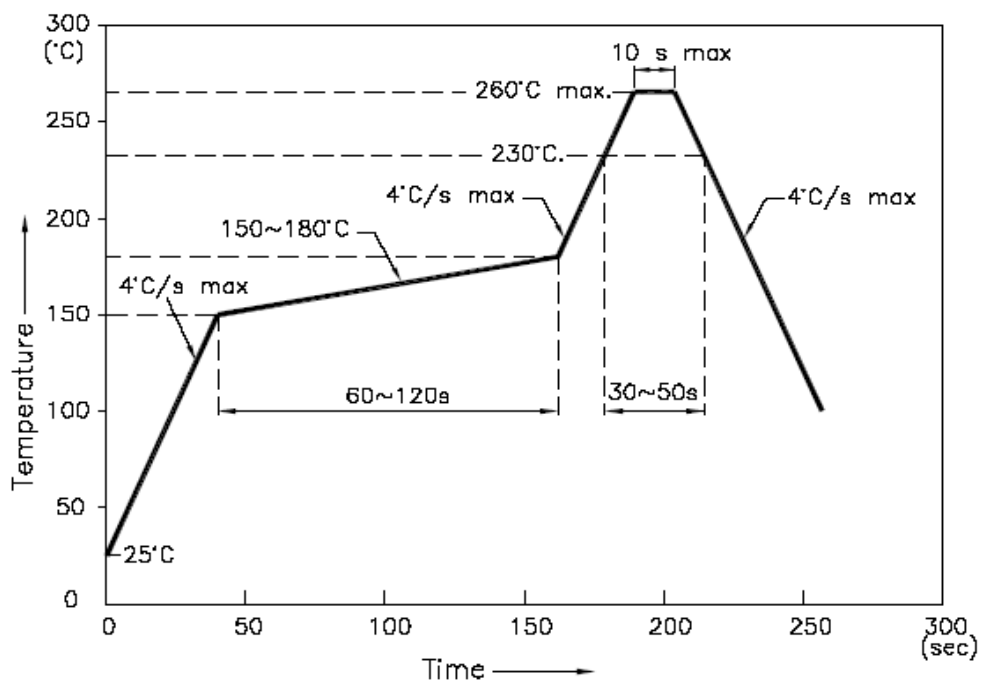
Tolerance:±0.005



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Precautions For Use :
Over - current - proof
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)
Storage
1. The operation of temperature and R.H. are : $5^{\circ}\text{C} \sim 30^{\circ}\text{C}$, 60%R.H. Max.
2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date) .
3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 15hrs.

■ Reflow Temp/Time



NOTES:

1. We recommend the reflow temperature $245^{\circ}\text{C} (\pm 5^{\circ}\text{C})$. the maximum soldering temperature should be limited to 260°C .
2. dont cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.



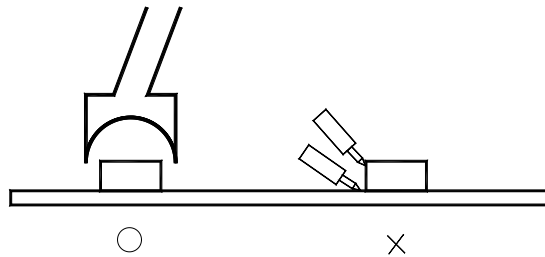
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■Soldering iron

Basic spec is $\leq 5\text{sec}$ when 260°C . If temperature is higher, time should be shorter ($+10^{\circ}\text{C} \rightarrow -1\text{sec}$). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C .

■Rework

1. Customer must finish rework within 5 sec under 260°C .
2. The head of iron can not touch copper foil
3. Twin-head type is preferred.



- Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow 、 solder etc.